

DATA SHEET

ANTI-SULFURATED CHIP RESISTORS

AF122 (4Pin/2R) / AF124 (8Pin/4R) / AF162 (4Pin/2R)/ AF164 (8Pin/4R) 5%, 1%

sizes 2 × 0402, 4 × 0402, 2 × 0603, 4 × 0603 RoHS compliant



YAGEO Phícomp



SCOPE

This specification describes AFI22/AFI24/AFI62/AFI64 (convex)series chip resistor arrays with lead-free terminations made by thick film process.

<u>APPLICATIONS</u>

- Terminal for SDRAM and **DDRAM**
- High-end Computer & Multimedia Electronics in high sulfur environment
- Consume electronic equipments: PDAs, PNDs
- Mobile phone, telecom...

FEATURES

- AEC-Q200 qualified
- RoHS compliant
- Reducing environmentally hazardous wastes
- High component and equipment reliability
- Saving of PCB space
- None forbidden-materials used in products/production
- Halogen Free Epoxy
- Moisture sensitivity level: MSL I

ORDERING INFORMATION - GLOBAL PART NUMBER & 12NC

Both part numbers are identified by the series, size, tolerance, packing type, temperature coefficient, taping reel and resistance value.

YAGEO BRAND ordering code

GLOBAL PART NUMBER (PREFERRED)

SERIES

AF XX X - X X X XX XXXX L

(1) (2) (3) (4) (5) (6)

(I) SIZE

 $12 = 0402 \times 2 (0404)$

 $12 = 0402 \times 4 (0408)$

 $16 = 0603 \times 2 (0606)$

 $16 = 0603 \times 4 (0612)$

(2) NUMBER OF RESISTORS

2 = 2 resistors

4 = 4 resistors

(3) TOLERANCE

 $F = \pm 1\%$

 $| = \pm 5\%$ (for jumper ordering, use code of |)

(4) PACKAGING TYPE

R = Paper taping reel

(5) TEMPERATURE COEFFICIENT OF RESISTANCE

- = Base on spec

(6) TAPING REEL

07 = 7 inch dia. Reel

13 = 13 inch dia, Reel

(7) RESISTANCE VALUE

There are 2~4 digits indicated the resistor value. Letter R/K/M is decimal point, no need to mention the last zero after R/K/M, e.g. I K2, not I K20.

Detailed resistance rules show in table of "Resistance rule of global part number".

Resistance rule of global part number

| Resistance code rule | Example | | |
|--------------------------------|--|--|--|
| 0R | 0R = Jumper | | |
| XRXX (1 to 9.76 Ω) | IR = I Ω IR5 = I.5 Ω 9R76 = 9.76 Ω | | |
| XXRX (10 to 97.6 Ω) | IOR = IO Ω 97R6 = 97.6 Ω | | |
| XXXR (100 to 976 Ω) | 100R = 100 Ω | | |
| XKXX (1 to 9.76 K Ω) | IK = 1,000 Ω 9K76 = 9760 Ω | | |
| XM (Ι ΜΩ) | ΙΜ = 1,000,000 Ω | | |

ORDERING EXAMPLE

The ordering code of a AF122 convex chip resistor array, value $1,000\Omega$ with ±5% tolerance, supplied in 7-inch tape reel is: AF122-JR-071KL.

NOTE

- I. All our R-Chip products meet RoHS compliant. "LFP" of the internal 2D reel label mentions "Lead Free Process"
- 2. On customized label, "LFP" or specific symbol printed and the optional "L" at the end of GLOBAL PART NUMBER

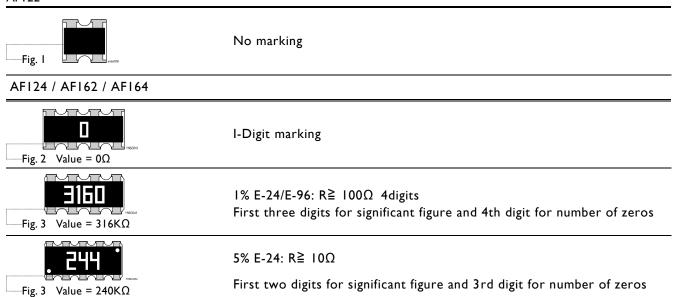


SERIES

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<u>MARKING</u>

AFI22

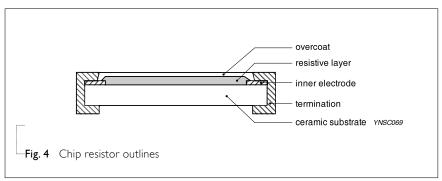


For further marking information, please refer to data sheet "Chip resistors marking".

CONSTRUCTION

The resistor is constructed on top of a high-grade ceramic body. Internal metal electrodes are added on each end to make the contacts to the thick film resistive element. The composition of the resistive element is a noble metal embedded into a glass and covered by a glass. The resistor is laser trimmed to the rated resistance value. The resistor is covered with a protective epoxy coat, finally the external terminations (matte tin on Nibarrier) are added as shown in Fig.4.

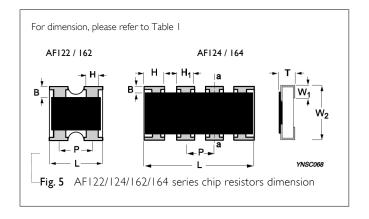
OUTLINES



DIMENSIONS

Table I

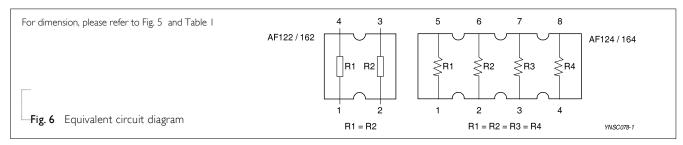
| 1 | | | | |
|---------------------|-----------------|-----------|--------------------|-----------|
| TYPE | AFI22 | AFI24 | AFI62 | AFI64 |
| B (mm) | 0.24±0.10 | 0.25±0.15 | 0.35 ± 0.10 | 0.35±0.15 |
| H (mm) | 0.30+0.10/-0.05 | 0.45±0.05 | 0.30 ± 0.10 | 0.65±0.05 |
| H_1 (mm) | | 0.30±0.05 | | 0.50±0.15 |
| P (mm) | 0.67±0.05 | 0.50±0.05 | 0.80 ± 0.05 | 0.80±0.05 |
| L (mm) | 1.00±0.10 | 2.00±0.10 | 1.60 ± 0.10 | 3.20±0.15 |
| T (mm) | 0.30±0.10 | 0.45±0.10 | 0.40 ± 0.10 | 0.60±0.10 |
| W _I (mm) | 0.25±0.10 | 0.30±0.15 | 0.30 ± 0.10 | 0.30±0.15 |
| W ₂ (mm) | 1.00±0.10 | 1.00±0.10 | 1.60 ± 0.10 | 1.60±0.15 |



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SCHEMATIC



ELECTRICAL CHARACTERISTICS

Table 2

| CHARACTERISTICS | | AFI22 | | AFI24 | | AFI62 | AFI | 64 |
|--------------------------|--|---------|--|---------|-----------------|---------|--|-----|
| Operating Temperature | -55 °C to + | -155 °C | −55 °C to - | +155 °C | −55 °C to | +155 °C | −55 °C to +155 | °C |
| Rated Power | | 1/16 W | | 1/16 W | | 1/16W | 1/16 | 5W |
| Maximum Working Voltage | | 50 V | | 25 V | | 50V | 5 | 50V |
| Maximum Overload Voltage | | 100 V | | 50 V | | 100V | 10 | V0C |
| Dielectric Withstanding | | 100 V | | 100 V | | 100V | 10 | 70V |
| Resistance Range | 5% (E24) I Ω to I M Ω I% (E24/E96) I0 Ω to I M Ω Jumper < 50 m Ω | | 5% (E24) Ι Ω t Ι% (E24/E96) Ι Ω t Jumper < | ο Ι ΜΩ | , | | 5% (E24) I Ω to I N (E24/E96) I Ω to I N Jumper < 50 n | MΩ |
| Temperature Coefficient | $I \Omega \le R \le I0 \Omega \pm 250 \text{ ppm/°C}$ $10 \Omega \le R \le I M\Omega \pm 200 \text{ ppm/°C}$ | | | | | | | |
| Jumper Criteria | Rated Current | 0.5 A | Rated Current | 1.0 A | Rated Current | 1.0 A | Rated Current 1. | Α0. |
| • | Maximum Current | 1.0 A | Maximum Current | 2.0 A | Maximum Current | 2.0 A | Maximum Current 2. | Α0. |

FOOTPRINT AND SOLDERING PROFILES

For recommended footprint and soldering profiles, please refer to data sheet "Chip resistors mounting".

PACKING STYLE AND PACKAGING QUANTITY

Table 3 Packing style and packaging quantity

| PACKING STYLE | REEL DIMENSION | AFI22 | AFI24 | AFI62 | AFI64 |
|-----------------------|----------------|--------------|--------------|-------------|--------------|
| Paper Taping Reel (R) | 7" (178 mm) | 10,000 units | 10,000 units | 5,000 units | 5,000 units |
| | 13" (330 mm) | 50,000 units | 40,000 units | | 20,000 units |

NOTE

1. For paper tape and reel specification/dimensions, please refer to data sheet "Chip resistors packing".



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FUNCTIONAL DESCRIPTION

POWER RATING

AFI22 / AFI24 / AFI62 / AFI64 rated power at 70 °C is I/16 W

RATED VOLTAGE

The DC or AC (rms) continuous working voltage corresponding to the rated power is determined by the following formula:

$$V = \sqrt{(P \times R)}$$

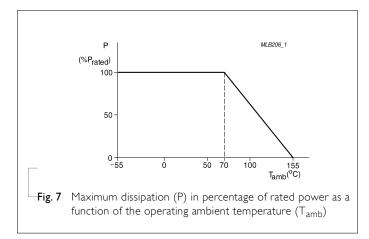
or max. working voltage whichever is less

Where

V=Continuous rated DC or AC (rms) working voltage (V)

P=Rated power (W)

R=Resistance value (Ω)

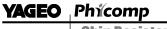


TESTS AND REQUIREMENTS

Table 4 Test condition, procedure and requirements

| TEST | TEST METHOD | PROCEDURE | REQUIREMENTS |
|---------------------------|------------------------|---|--|
| Life/ | MIL-STD-202-method 108 | 1,000 hours at 70±2 °C applied RCWV | ±(2%+0.05 Ω) |
| Endurance | IEC 60115-1 4.25 | 1.5 hours on, 0.5 hour off, still air required | <100 m Ω for Jumper |
| High Temperature Exposure | MIL-STD-202-method 108 | I,000 hours at maximum operating temperature depending on specification, unpowered | \pm (1%+0.05 Ω) <50 m Ω for Jumper |
| | | Tolerances: I55±3 °C | |
| Moisture | MIL-STD-202-method 106 | Each temperature / humidity cycle is defined at | ±(2%+0.05 Ω) |
| Resistance | | 8 hours (method 106G), 3 cycles / 24 hours for 10d with 25 $^{\circ}$ C / 65 $^{\circ}$ C 95% R.H, without steps 7a & 7b, unpowered | <100 m Ω for Jumper |
| | | Parts mounted on test-boards, without condensation on parts | |
| | | Measurement at 24±2 hours after test conclusion | |
| Thermal Shock | MIL-STD-202-method 107 | -55/+125 °C | ±(1%+0.05 Ω) |
| | | Note: Number of cycles required is 300. Devices mounted | $<$ 50 m Ω for Jumper |
| | | Maximum transfer time is 20 seconds. Dwell time is 15 minutes. Air – Air | |
| Short Time | IEC60115-1 4.13 | 2.5 times RCWV or maximum overload voltage whichever is less for 5 sec at room temperature | ±(2%+0.05 Ω) |
| Overload | | | $<$ 50 m Ω for Jumper |
| | | | No visible damage |
| Board Flex/ Bending | IEC60115-1 4.33 | Device mounted on PCB test board as | ±(1%+0.05 Ω) |
| | | described, only I board bending required | $<$ 50 m Ω for Jumper |
| | | 3 mm bending | No visible damage |
| | | Bending time: 60±5 seconds Ohmic value checked during bending | |
| | | Statile value checked during bending | |





Chip Resistor Surface Mount AF

SERIES 122/124/162/164 (RoHS Compliant)

| TEST | TEST METHOD | PROCEDURE | REQUIREMENTS |
|-----------------|------------------------|---|------------------------------|
| Solderability | | | |
| - Wetting | J-STD-002 test B | Electrical Test not required | Well tinned (≥95% covered) |
| | | Magnification 50X | No visible damage |
| | | SMD conditions: | |
| | | I st step: method B, aging 4 hours at 155 °C dry heat | |
| | | 2 nd step: leadfree solder bath at 245±3 °C | |
| | | Dipping time: 3±0.5 seconds | |
| - Leaching | J-STD-002 test D | Leadfree solder, 260 °C, 30 seconds immersion time | No visible damage |
| - Resistance to | IEC 60115-1 4.18 | Condition B, no pre-heat of samples | ±(1%+0.05Ω) |
| Soldering Heat | MIL-STD-202 Method 215 | Leadfree solder, 260 °C, 10 seconds immersion time | <50 m Ω for Jumper |
| | | | No visible damage |
| | | Procedure 2 for SMD: devices fluxed and cleaned with isopropanol | · |
| FOS | ASTM-B-809-95* | Sulfur 750 hours, 105°C, unpowered | ±(4.0%+0.05Ω) |
| | *Modified | | $<$ 100m Ω for Jumper |

REVISION HISTORY

| REVISION | DATE | CHANGE NOTIFICATION | DESCRIPTION |
|-----------|---------------|---------------------|---|
| Version 5 | Mar. 20, 2017 | - | - Modify AF124/164 Equivalent Circuit Diagram |
| Version 4 | Jun. 23, 2016 | - | - AEC-Q200 qualified |
| Version 3 | Nov. 17, 2015 | - | - Add in AF162 |
| Version 2 | May 29,2015 | - | - Add in AF164 |
| Version I | Aug. 15, 2014 | - | - Update AFI24 dimensions |
| Version 0 | Oct. 02, 2013 | - | - First issue of this specification |

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